

/ Revised record

A	2020-8-7	ALL			

/ Descriptions

50V~1000V 2.0A SMA

Surface Mount Fast Recovery Rectifiers, Reverse Voltage 50 to1000V,Forward Current:2.0A ,SMA package.

/ Features

RoHS 2011/65/EU

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

/ Applications

General purpose.

/ E



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T _c = 125 °C	I _{F (AV)}	2.0							A
Peak Forward Surge Current 8.3 ms Single HalfSine Wave Superimposed on Rated Load	I _{FSM}	50							A
Typical Junction Capacitance at V _R =4V f=1MHz	C _j	22							pF
Typical Thermal Resistance ¹⁾	R _{θJA}	65							°C/W
	R _{θJC}	20							
Operating and Storage Temperature Range	T _j , T _{stg}	-55~+150							°C

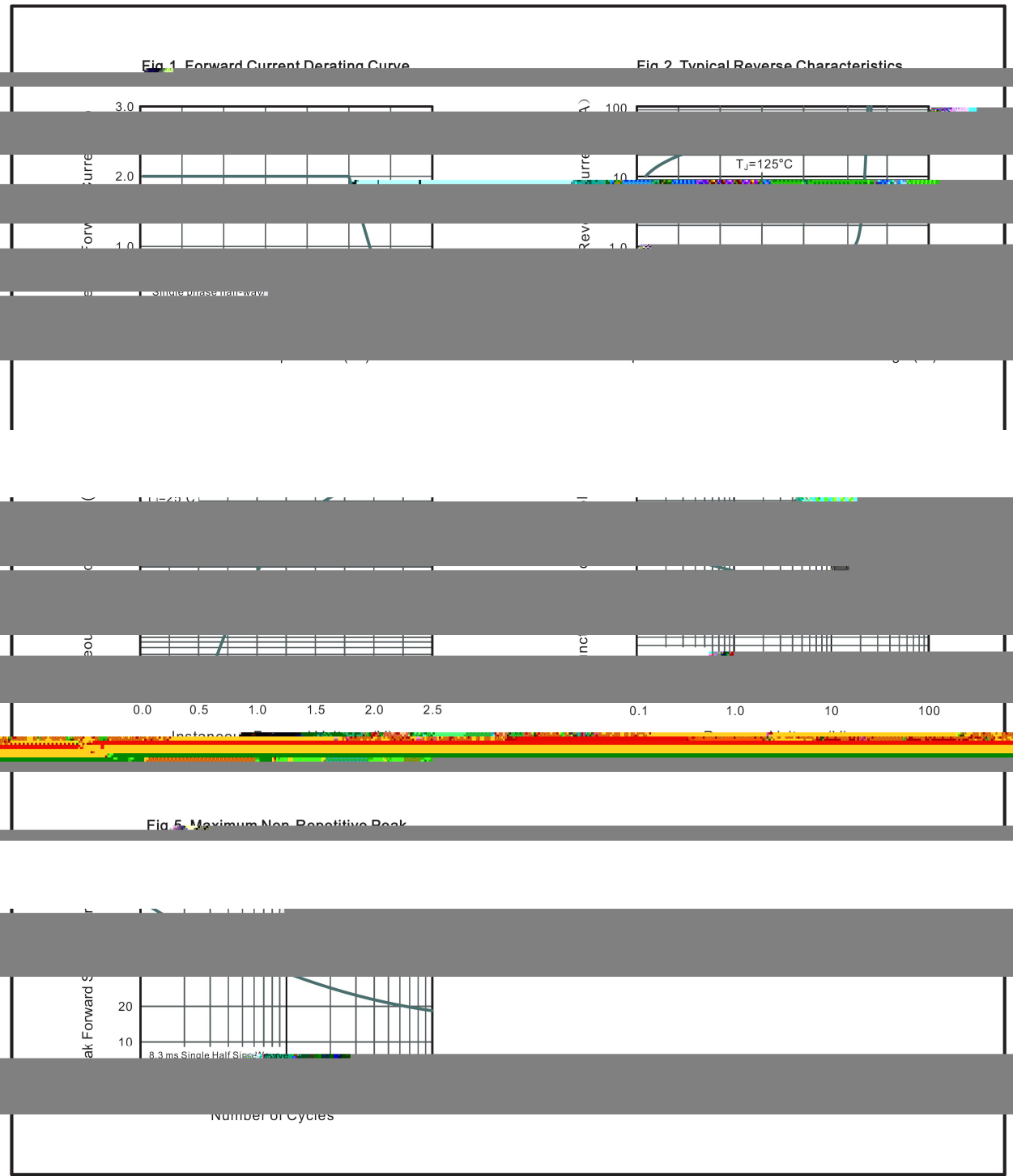
Note:

1) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

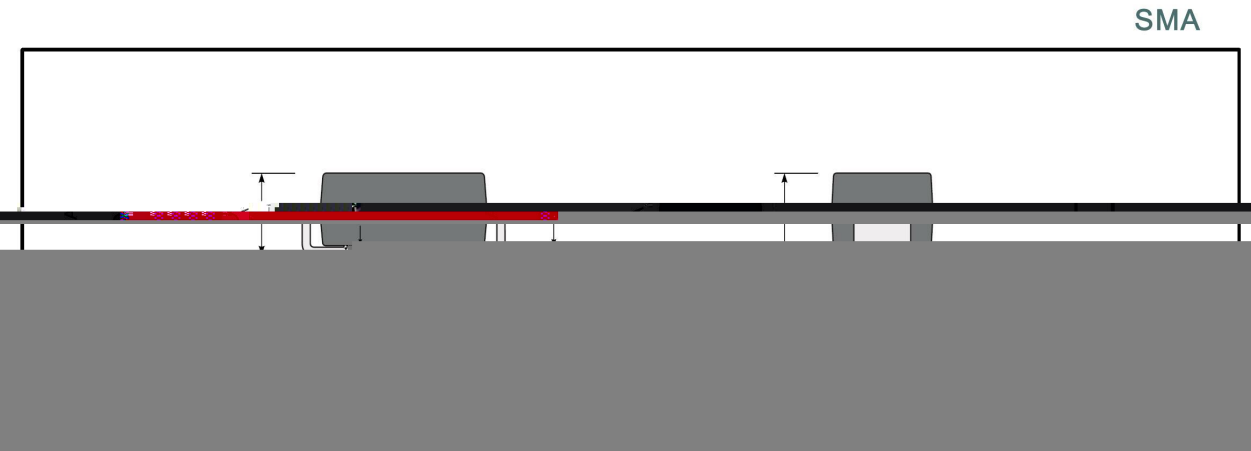
/ Electrical Characteristics(Ta=25)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	
Maximum Instantaneous Forward Voltage	V_F	$I_F=2.0\text{A}$	1.3							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	5.0							μA
		$T_a=125^\circ\text{C}$	100							μA
Maximum Reverse Recovery Time	t_{rr}	$I_F = 0.5\text{ A}$ $I_R = 1\text{ A}$ $I_{rr} = 0.25\text{ A}$	150				250	500		ns

/ Electrical Characteristic Curve

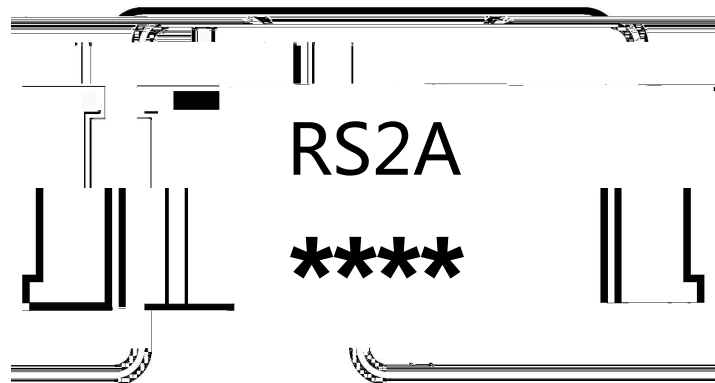


/ Package Dimensions



UNIT	A	D	E	H _E	c	e	q	a ₁
mm	1.9	4.0	2.3	1.7	0.15	1.3	0.0	0.0

/ Marking Instructions



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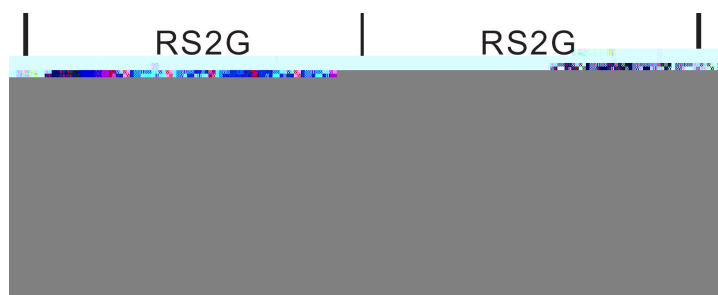
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Note:

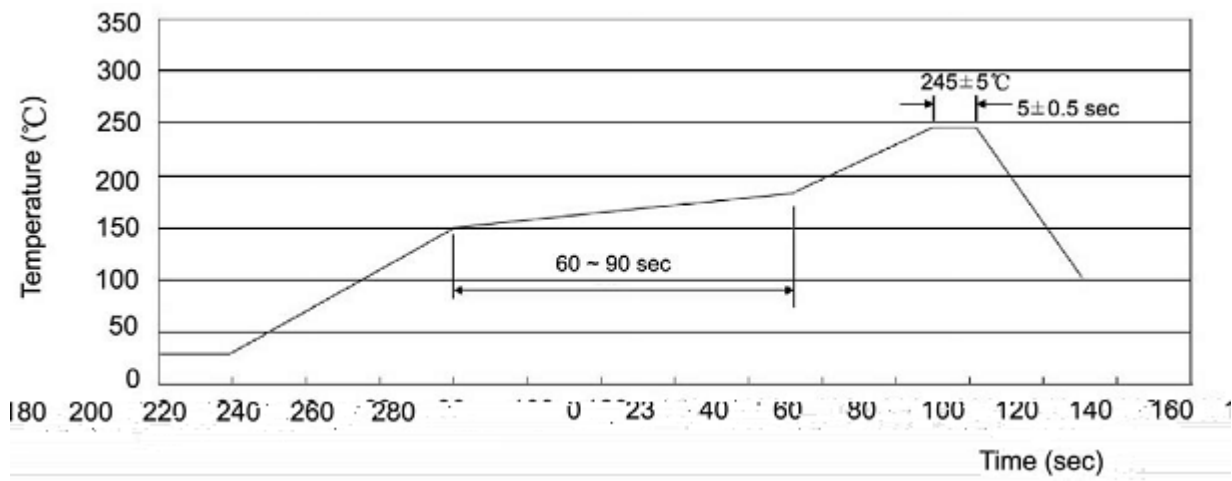
Product Type Code

Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

Marking



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec
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/ REEL

Package Type	Units	Dimension
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